



Semiconductor Device Type: N3X-SOIC-28-.300in-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				30.49	100.00%	3.86%		
	Silicon	7440-21-3	30.49		100.00%		3.86%	38600
Mold Compound				601.66	100.00%	76.16%		
	o-Cresol-epichlorohydrin-formaldehyde Copolymer	29690-82-2	18.05		3.00%		2.28%	22848
	Epoxy Resin	Trade Secret	48.13		8.00%		6.09%	60928
	Silica (Fused)	60676-86-0	484.34		80.50%		61.31%	613088
	Phenolic Resin	Trade Secret	48.13		8.00%		6.09%	60928
	Carbon Black	1333-86-4	3.01		0.50%		0.38%	3808
Lead Frame				138.42	100.00%	17.52%		
	Copper	7440-50-8	134.91		97.46%		17.08%	170775
	Iron	7439-89-6	3.23		2.33%		0.41%	4089
	Phosphorus	7723-14-0	0.11		0.08%		0.01%	137
	Zinc	7440-66-6	0.17		0.12%		0.02%	210
	Lead	7439-92-1	0.01		0.00%		0.00%	8
Lead Frame Plating				9.31	100.00%	1.18%		
	Silver	7440-22-4	9.31		100.00%		1.18%	11781
Bond Wire				0.47	100.00%	0.06%		
	Gold	7440-57-5	0.47		100.00%		0.06%	600
Die Attach				5.61	100.00%	0.71%		
	Formaldehyde, Polymer with 2-(chloromethyl)oxirane and Phenol	9003-36-5	0.56		10.00%		0.07%	710
	2,2'-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bis[oxirane]	13561-08-5	0.56		10.00%		0.07%	710
	Silver	7440-22-4	3.93		70.00%		0.50%	4970
	Dimer Acid Diglycidyl Ester	68475-94-5	0.56		10.00%		0.07%	710
Plating and Anode Ball				4.03	100.00%	0.51%		
	Tin	7440-31-5	4.02		99.90%		0.51%	5095
	Miscellaneous	Trade Secret	0.00		0.10%		0.00%	5
<b>Totals</b>			<b>790.00</b>	<b>790.00</b>		<b>100.00%</b>	<b>100.00%</b>	<b>1000000</b>

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